

φ0.080 Ultra Micro-Hole Drilling Performance

φ0.080 ドリル 加工事例

用途:半導体パッケージ、各種デバイス用基板 等 FBGA、BGA、Device substrate etc...

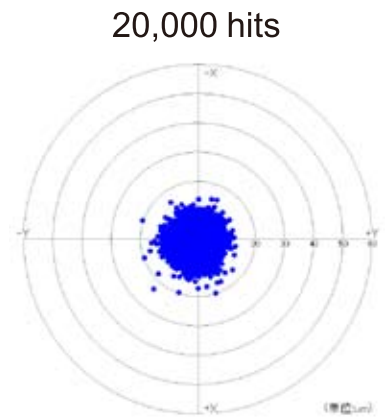
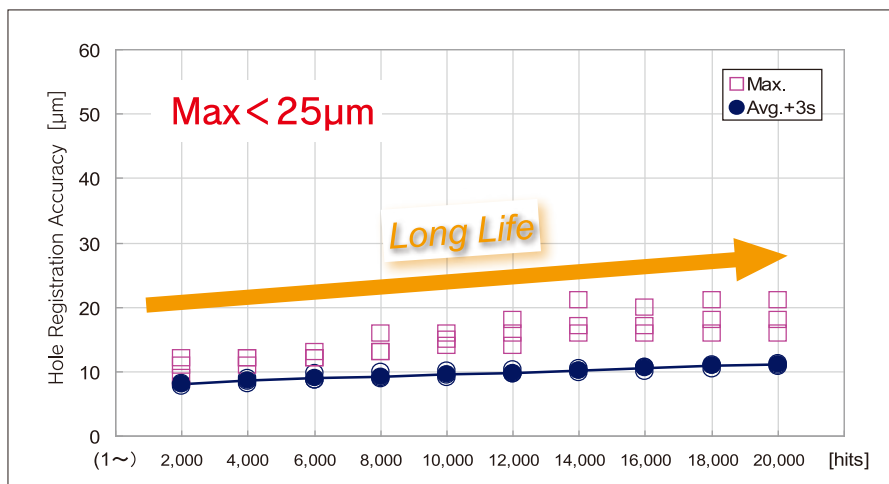
Drilling Condition 加工条件

Work Material : MCL-E-679FG(RM) t0.1(Double Sided) x 4 stack height 5/5μmCopper

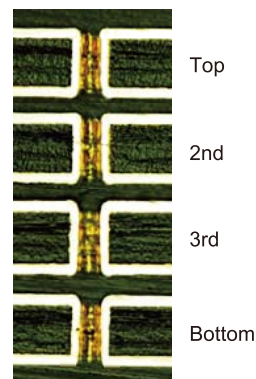
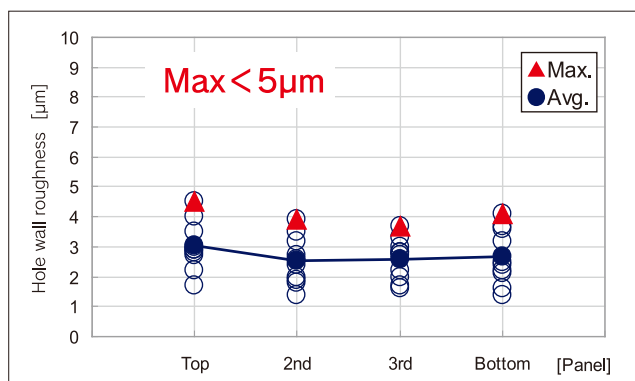
S : 350,000 min⁻¹ F : 1.75 m/min f : 5 μm/rev

Set Life : 20,000 hits

Hole Registration Accuracy 穴位置精度



Hole Wall Quality at 20,000th hit 内壁粗さ



'08JPCA展示データ
 Work Material : MCL-E-679FG(R)
 t0.1(Double Sided) x 4 stack height (4/4μmCopper)
 Set Life : 10,000hits
 Hole Registration Accuracy : Max<20μm
 Hole Wall Quality at 10,000hits : Max<4μm

Tool life 200%
 加工寿命200%
 Continuous high quality
 高品質を維持